



Material Content Data Sheet



Sales Product Name		ICB2FL01G		Issued		22. January 2018		
MA#		MA001234154						
Package		PG-DSO-19-5		Weight*		582.34 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.879	1.01	1.01	10096	10096
leadframe	inorganic material	phosphorus	7723-14-0	0.040	0.01		69	
	non noble metal	zinc	7440-66-6	0.160	0.03		275	
	non noble metal	iron	7439-89-6	3.200	0.55		5495	
wire	non noble metal	copper	7440-50-8	129.929	22.31	22.90	223117	228956
	noble metal	gold	7440-57-5	0.432	0.07	0.07	741	741
	encapsulation	organic material	carbon black	1333-86-4	1.309	0.22		2247
plastics		epoxy resin	-	42.312	7.27		72659	
	inorganic material	silicondioxide	60676-86-0	392.589	67.42	74.91	674159	749065
leadfinish	non noble metal	tin	7440-31-5	3.337	0.57	0.57	5730	5730
plating	noble metal	silver	7440-22-4	0.174	0.03	0.03	299	299
glue	plastics	acrylic resin	-	0.596	0.10		1023	
	noble metal	silver	7440-22-4	2.382	0.41	0.51	4090	5113
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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